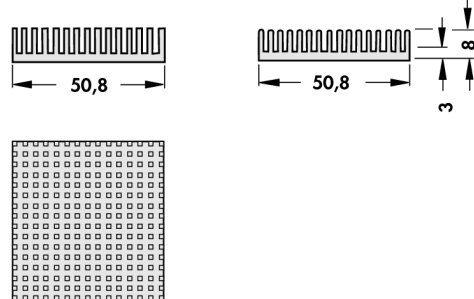
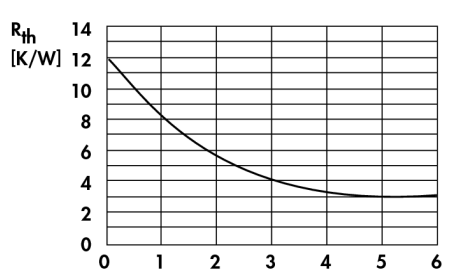
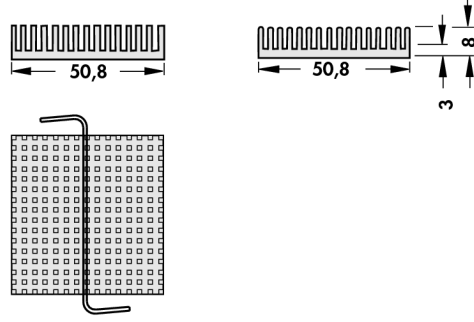
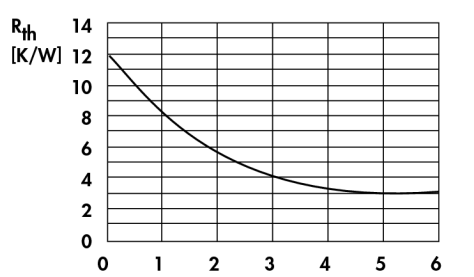
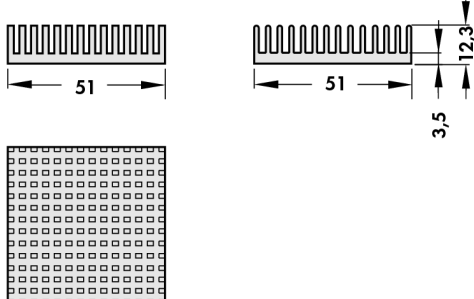
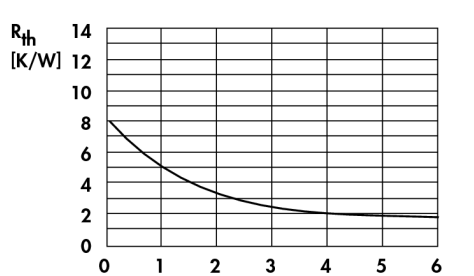
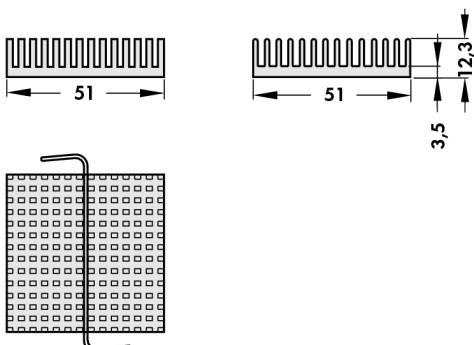
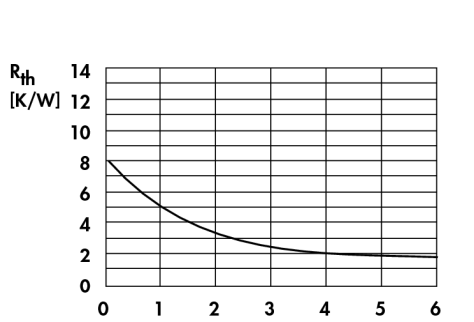
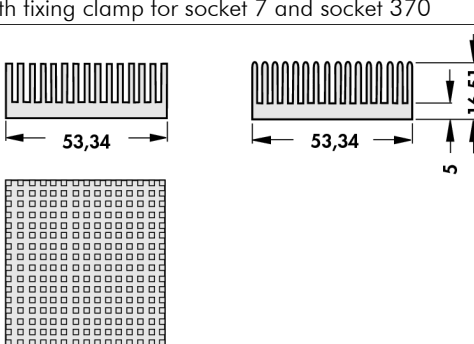
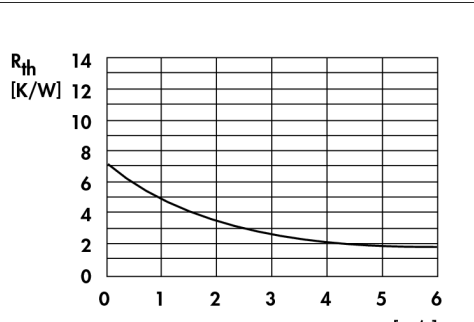


Heatsinks for PGA

<p>art. no.</p> <p>ICK PGA 20 x 20 x 8 WLF ... 50 x 50</p>		
<p>art. no.</p> <p>ICK PGA 20 x 20 x 8 K WLF ... 50 x 50</p>		
<p>art. no.</p> <p>ICK PGA 20 x 20 x 12 WLF ... 50 x 50</p>		
<p>art. no.</p> <p>ICK PGA 20 x 20 x 12 K WLF ... 50 x 50</p>		
<p>art. no.</p> <p>ICK PGA 21 x 21 WLF ... 53 x 53</p>		

B 11

Thermal conduct. foil WLFT 404/405 → E 5
 Thermal conductive glue → E 14
 Thermal conductive paste → E 12
 Processor overview → B 2 - 7

SMD-heatsinks → B 25 - 27
 Mounting material for semiconduct. → E 34 - 38
 Hole pattern → A 21
 Technical introduction → A 2 - 7